

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	21	(silicon semiconductor) same ceramic same (submount mount) same (TCE thermal adj coefficient)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/26 09:50
L2	5	((("20010194564") or ("6519728") or ("6400173") or ("20020171449") or ("20030006795") or ("20030032263"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/05/26 10:10
L3	5	((("6261467") or ("5933709") or ("4835593") or ("6255729") or ("6456099"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/05/26 10:10
L4	2794	(714/724,726,727).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/05/26 10:10
L5	1119	boundary scan test	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/26 10:10
L6	134	L5 and internal scan	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/26 10:10
L7	121	L6 and (board pcb mount mounting substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/26 10:10
L8	93	L7 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/26 10:10
L9	319	L5 and L4	US-PGPUB; USPAT; USOCR	ADJ	OFF	2006/05/26 10:10
L10	1090	(257/48).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/05/26 10:10
L11	78	L8 and chip	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/26 10:10

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L12	21	L5 and internal scan chain	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/26 10:10
L13	18	L12 and (board pcb mount mounting substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/26 10:10
L14	11	L13 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/26 10:10
L15	11	L14 and input and output	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/26 10:10
L16	1	(US-20040195672-\$ or US-20040197941-\$).did. or (US-6734549-\$).did.	US-PGPUB; USPAT	OR	OFF	2006/05/26 10:10
L17	11	L13 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/26 10:10
L18	8	L14 and input terminal and output terminal	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/05/26 10:10
L19	6	((("20020194564") or ("6519728") or ("6400173") or ("20020171449") or ("20030006795") or ("20030032263")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/05/26 10:10
L20	2	(US-20030032263-\$ or US-20030006795-\$).did.	US-PGPUB	OR	OFF	2006/05/26 10:10
L21	121	boundary scan and scan chain and IP	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/26 10:10
L22	90	L21 and (silicon semiconductor gaas inp)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/26 10:10
L23	51	interface with two-wire adj type	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/26 10:10

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L24	90	L22 and (test tested testing tester test adj frame)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/26 10:10
L25	40	L23 and (test tested testing tester test adj frame)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/26 10:10
L26	66	chip adj IP and IP	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/26 10:10
L27	18	IP Super-Sub	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/26 10:10
L28	47	chip adj IP and IP and intellectual adj property	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/05/26 10:10
L29	41884	fukuyama or Oki Electric	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/26 10:10
L30	6	boundary scan and scan chain and L29	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2006/05/26 10:10
L31	5	("6094736" "6272069" "6473873" "6519171" "6711042").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/05/26 10:10
L32	4	L31 and (boundary or scan or chain or test or testing or tested)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/05/26 10:10
L33	25411	multi-chip package or MCP or multi-chip module or MCM	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/05/26 10:10
L34	1617	(multi-chip package or MCP or multi-chip module or MCM) near3 (semiconductor or silicon)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/05/26 10:10

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L35	26	boundary scan and L34	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/05/26 10:10
L36	12	scan chain and L34	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/05/26 10:10
L37	6	L35 and L36	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/05/26 10:10